

THERMAL INTERMEDIATE APPARATUS, SYSTEMS, AND METHODS

Abstract of the Disclosure

- 5 Apparatus and system, as well as fabrication methods therefor, may include a thermal intermediate structure comprised of a plurality of carbon nanotubes some of which have organic moieties attached thereto to tether the nanotubes to at least one of a die and a heat sink. The organic moieties include thiol linkers and amide linkers.

"Express Mail" mailing label number: EV 370239524 US

Date of Deposit: December 30, 2003

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